

April 2013

FAN7527B Power Factor Correction Controller

Features

- Internal Startup Timer
- Internal R/C Filter Eliminates the Need for External R/C Filter
- Precise Adjustable Output Over-Voltage Protection
- Zero Current Detector
- One Quadrant Multiplier
- Trimmed 1.5% Internal Band Gap Reference
- Under-Voltage Lockout with 3 V of Hysteresis
- Totem-Pole Output with High-State Clamp
- Low Startup and Operating Current
- 8-Pin SOP or 8-Pin DIP

Applications

- Electronic Ballast
- SMPS

Description

The FAN7527B provides simple and high-performance active Power Factor Correction (PFC). The FAN7527B is optimized for electronic ballasts and low-power, high-density power supplies that require minimum board size, reduced external components, and low power dissipation. Because the R/C filter is included in the current-sense block, an external R/C filter is not necessary. Special circuitry prevents no-load runaway conditions. Regardless of the supply voltage, the output drive clamping circuit limits the overshoot of the power MOSFET gate drive, which improves system reliability.



Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method	
FAN7527BMX -25 to +125°C		8-Lead, Small Outline Package (SOP)	Tape and Reel	
FAN7527BN -25 to +125°C		8-Lead, Dual Inline Package (DIP)	Tube	

Block Diagram

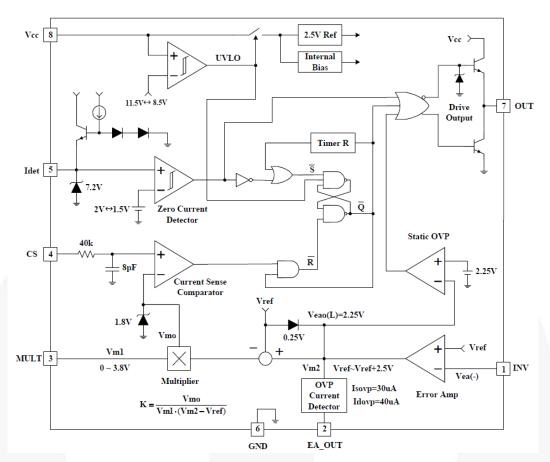


Figure 1. Block Diagram

Pin Configuration

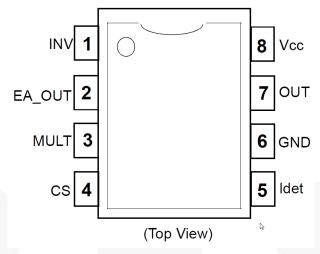


Figure 2. Pin Configuration

Pin Definitions

Pin#	Name	Description	
1	INV	Inverting input of the error amplifier. The output of the boost converter should be resistively divided to 2.5 V and connected to this pin.	
2	EA_OUT	Output of the error amplifier. Feedback compensation network is placed between this pin and the INV pin.	
3	MULT	Input to the multiplier stage. The full-wave rectified AC voltage is divided to less than 2 V and is connected to this pin.	
4	CS	nput of the PWM comparator. The MOSFET current is sensed by a resistor and the resulting oltage is applied to this pin. An internal R/C filter is included to reject high-frequency noise.	
5	ldet	Zero Current Detection (ZCD) input.	
6	GND	Ground	
7	OUT	Sate driver output. Push-pull output stage is able to drive the power MOSFET with a peak current of 500 mA.	
8	V _{CC}	Supply voltage of driver and control circuits.	

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter			Max.	Unit
V _{CC}	Supply Voltage			30	V
I _{OH} , I _{OL}	Peak Drive Output Current			±500	mA
I _{CLAMP}	Driver Output Clamping Diodes Vo > Vc	_C or V _O <-0.3 V		±10	mA
I _{DET}	Detector Clamping Diodes			±10	mA
V _{IN}	Error Amplifier Multiplier and Comparato	-0.3	6.0	V	
TJ	Operation Junction Temperature		+150	°C	
T _{OPR}	Operating Temperature Range	-25	+125	°C	
T _{STG}	Storage Temperature Range		-65	+150	°C
ь /	Davier Dissipation	8-SOP		0.8	W
P _D	Power Dissipation	8-DIP		1.1	W
0	The second Decision and Long time Archivet	8-SOP		150	°C/W
Θ_{JA}	Thermal Resistance Junction-Ambient	8-DIP		110	°C/W

Temperature Characteristics

 $-25^{\circ}\text{C} \le \text{T}_{\text{A}} \le 125^{\circ}\text{C}$.

Symbol	Parameter		Тур.	Max.	Unit
ΔV_{REF}	Temperature Stability Reference Voltage (V _{REF})		20		mV
ΔΚ/ΔΤ	Temperature Stability for Multiplier Gain (K)		-0.2		%/°C

Electrical Characteristics

 V_{CC} = 14 V, -25°C ≤ T_A ≤ 125°C, unless otherwise stated.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Under-Volta	ge Lockout		•		1	
V _{th(st)}	Start Threshold Voltage	V _{CC} Increasing	10.5	11.5	12.5	V
H _{Y(st)}	UVLO Hysteresis		2	3	4	V
Supply Curr	ent Section		•		-	
I _{ST}	Startup Supply Current	$V_{CC} = V_{th(st)}$ -0.2 V	10	60	100	μA
I _{cc}	Operating Supply Current	Output Not Switching		3	6	mA
I _{CC(OVP)}	Operating Current at OVP	V _{INV} = 3 V		1.7	4.0	mA
I _{DCC}	Dynamic Operating Supply Current	50 kHz, C _I = 1 nF	-/	4	8	mA
Error Ampli	fier Section					
V	Note we Feedback to well the selection	I _{REF} = 0 mA, T _A = 25°C	2.465	2.500	2.535	
V_{REF}	Voltage Feedback Input Threshold	25°C ≤ T _A ≤ 125°C	2.440	2.500	2.560	V
ΔV_{FEF1}	Line Regulation	14 V ≤ V _{CC} ≤ 25 V		0.1	10.0	mV
ΔV_{FEF3}	Temperature Stability of V _{REF} ⁽¹⁾	-25°C ≤ T _A ≤ 125°C		20		mV
I _{b(ea)}	Input Bias Current		-0.5	Δ,,	0.5	μA
I _{SOURCE}	Output Source Current	V _{M2} = 4 V	-2	-4		mA
I _{SINK}	Output Sink Current	V _{M2} = 4 V	2	4		mA
V _{EAO(H)}	Output Upper Clamp Voltage ⁽¹⁾	I _{SOURCE} = 0.1 mA		6		V
V _{EAO(L)}	Output Lower Clamp Voltage ⁽¹⁾	I _{SINK} = 0.1 mA		2.25		V
G _V	Large Signal Open-Loop Gain ⁽¹⁾	y y	60	80		dB
PSRR	Power Supply Rejection Ratio ⁽¹⁾	14 V ≤ V _{CC} ≤ 25 V	60	80		dB
GBW	Unity Gain Bandwidth ⁽¹⁾			1		MHZ
SR	Slew Rate ⁽¹⁾			0.6		V/µs
Multiplier Se	ection				7	
I _{b(m)}	Input Bias Current (Pin 3)		-0.5		0.5	μΑ
ΔV_{M1}	M1 Input Voltage Range (Pin 3)				3.8	V
ΔV_{M2}	M2 Input Voltage Range (Pin 2)		V_{REF}		V _{REF} +2.5	V
K	Multiplier Gain ⁽¹⁾	$V_{M1} = 1 \text{ V}, V_{M2} = 3.5 \text{ V}$	0.36	0.44	0.52	1 / V
$V_{OMAX(m)}$	Maximum Multiplier Output Voltage	V _{INV} =0 V, V _{M1} = 4 V	1.65	1.80	1.95	V
$\Delta K/\Delta T$ Temperature Stability of $K^{(1)}$		-25 ≤ T _A ≤ 125°C		-0.2	V	%/°C
Current Sen	se Section					
$V_{IO(CS)}$	Input Offset Voltage ⁽¹⁾	$V_{M1} = 0 \text{ V}, V_{M2} = 2.2 \text{ V}$	-10	3	10	mV
I _{b(CS)}	Input Bias Current	0 V ≤ V _{CS} ≤ 1.7 V	-1.0	-0.1	1.0	μA
t _{D(CS)}	Current Sense Delay to Output ⁽¹⁾			200	500	ns

Continued on the following page...

Electrical Characteristics (Continued)

 V_{CC} = 14 V, -25°C ≤ T_A ≤ 125°C, unless otherwise stated.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Zero Curren	t Detect Section		•	•	•	
V _{TH(DET)}	Input Voltage Threshold	V _{DET} Increasing	1.7	2.0	2.3	V
H _{Y(DET)}	Detect Hysteresis		0.2	0.5	0.8	V
$V_{CLAMP(I)}$	Input Low Clamp Voltage	I _{DET} = -100 μA	0.45	0.75	1.00	V
V _{CLAMP(H)}	Input High Clamp Voltage	I _{DET} = 3 mA	6.5	7.2	7.9	V
I _{b(DET)}	Input Bias Current	1 V ≤ V _{DET} ≤ 5 V	-1.0	-0.1	1.0	μΑ
I _{CLAMP(D)}	Input High/Low Clamp Diode Current ⁽¹⁾				±3	mA
Output Sect	tion					
V _{OH}	Output Voltage High	I _O = -10 mA	10.5	11.0		V
V _{OL}	Output Voltage Low	I _O = 10 mA		0.8	1.0	V
t _R	Rising Time ⁽¹⁾	C _L = 1 nF		130	200	ns
t _F	Falling Time ⁽¹⁾	C _L = 1 nF		50	120	ns
V _{OMAX(O)}	Maximum Output Voltage	$V_{CC} = 20 \text{ V}, I_{O} = 100 \mu\text{A}$	12	14	16	V
$V_{OMIN(O)}$	Output Voltage with UVLO Activated	$V_{CC} = 5 \text{ V}, I_{O} = 100 \mu\text{A}$		\	1	V
Restart Time	er Section					
t _{D(RST)}	Restart Time Delay	$V_{M1} = 1 \text{ V}, V_{M2} = 3.5 \text{ V}$		150		μs
Over-Voltag	e Protection Section					
I _{SOVP}	Soft OVP Detecting Current		25	30	35	μA
I _{DOVP}	Dynamic OVP Detecting Current		35	40	45	μΑ
V _{OVP}	Static OVP Threshold Voltage	$V_{INV} = 2.7 \text{ V}$	2.10	2.25	2.40	V

Note:

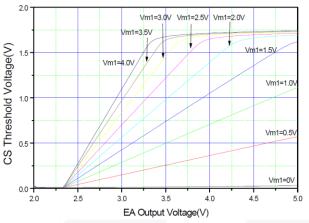
1. These parameters, although guaranteed, are not 100% tested in production.

Multiplier Gain:

$$K = \frac{Pin4_Threshold}{V_{M1} \times (V_{M2} - V_{REF})}$$

where $V_{M1} = V_{PIN3}$, $V_{M2} = V_{PIN2}$

Typical Performance Characteristics



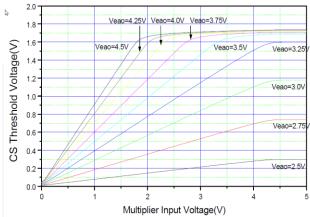


Figure 3. Error Amplifier Output Voltage vs. Current Sensing Threshold

0.015

0.012

(V) 0.009

0.006

(V) 0.006

2.7

2.6

(V) 0.009

2.5

2.7

Figure 4. Multiplier Input Voltage vs. Current Sensing Threshold

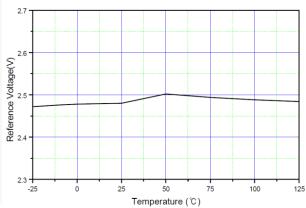


Figure 5. Supply Current vs. Supply Voltage

Supply Voltage(V)

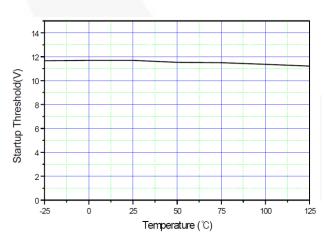


Figure 6. Reference Voltage vs. Temperature

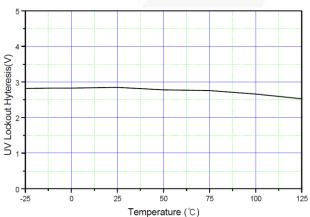


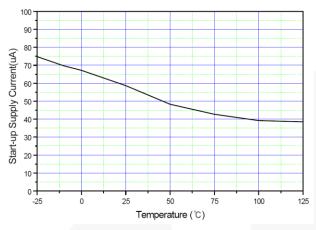
Figure 7. Startup Threshold vs. Temperature

Figure 8. UVLO Hysteresis vs. Temperature

0.003

0.000

Typical Performance Characteristics (Continued)



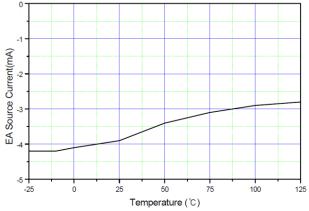
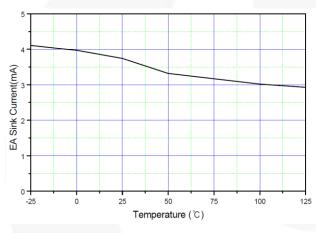


Figure 9. Startup Supply Current vs. Temperature

Figure 10. Error Amplifier Source Current



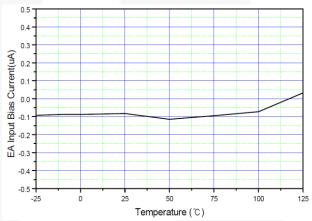
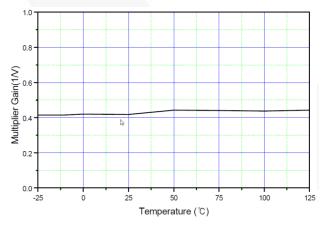


Figure 11. Error Amplifier Sink Current vs. Temperature

Figure 12. Error Amplifier Input Bias Current vs. Temperature



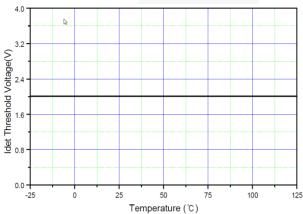
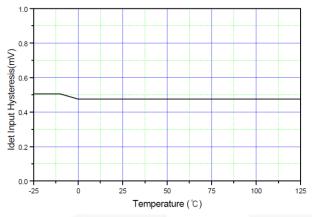


Figure 13. Multiplier Gain vs. Temperature

Figure 14. I_{DET} Threshold Voltage vs. Threshold

Typical Performance Characteristics (Continued)



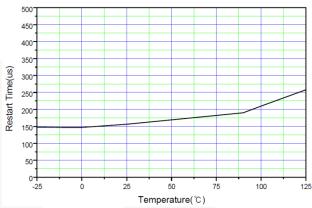
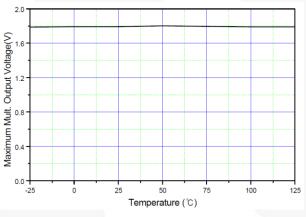


Figure 15. IDET Input Hysteresis vs. Temperature

Figure 16. Restart Time vs. Temperature



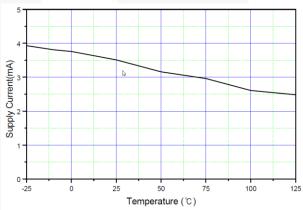
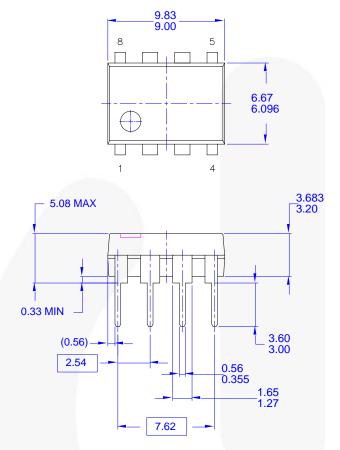
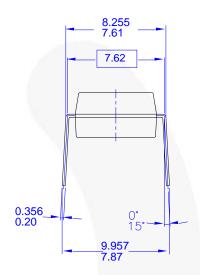


Figure 17. Maximum Multiplier Output Voltage vs. Temperature

Figure 18. Supply Current vs. Temperature

Physical Dimensions





NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-001 VARIATION BA
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994
- E) DRAWING FILENAME AND REVSION: MKT-N08FREV2.

Figure 19. 8-Lead, MDIP, .300" Wide, Two DAP

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Physical Dimensions (8-SOP)

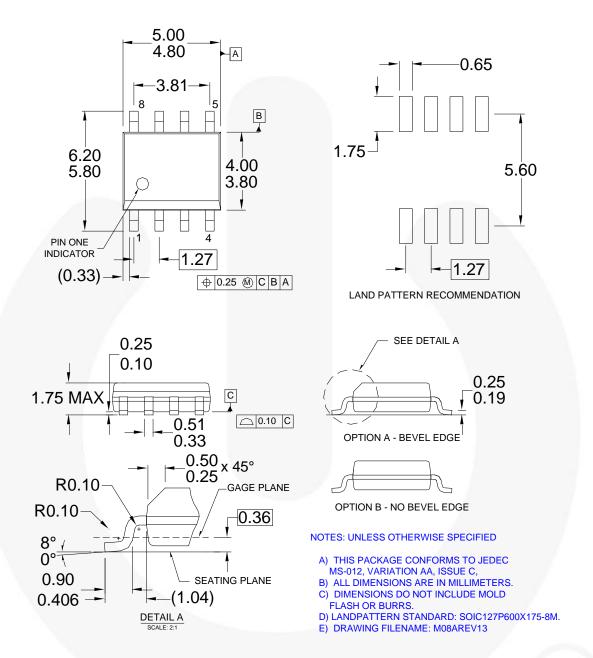


Figure 20. 8-Lead, Small Outline Package

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